IN THE CLAIMS:

Please amend Claims 1, 9, 14, 15 and 18 as shown below. The claims, as pending in the subject application, read as follows:

1. (Currently Amended) A semiconductor device for transmitting information by using an induction field as a transmission medium, comprising:

an IC chip for storing and processing information to be transmitted;

an IC chip supporting section for mounting the IC chip thereon;

a coil for generating the induction field;

connecting terminals provided at an end of the coil;

wires connecting the IC chip and the connecting terminals;

sheets of tape bonding and fixing a part of one side of the coil; and

a resin integrating the IC chip, the IC chip supporting section, the coil, the wires, the connecting terminals, and the sheets of tape with one another,

wherein the IC chip supporting section, the coil, and the connecting terminals are formed of the same metal plate that is patterned, and

wherein at least one side of the coil is exposed to air from a surface of the resin.

2 to 8. (Cancelled)

9. (Currently Amended, Withdrawn) A method of producing a semiconductor device that transmits information by using as a transmission medium an induction field generated

from a coil electrically connected to an IC chip for storing and processing information to be transmitted, comprising the steps of:

preparing one sheet of a metal plate;

forming a metal frame having at least a coil pattern, an IC chip supporting section, and a connecting terminal pattern formed at an end of the coil pattern, by patterning the metal plate;

mounting the IC chip on the IC chip supporting section;

electrically connecting the connecting terminal pattern to the IC chip using wires;

bonding and fixing a part of one side of the coil pattern using sheets of tape; and

integrating the IC chip, the IC chip supporting section, the coil pattern, the wires, the sheets of tape and the metal frame with a resin such that at least one side of the coil pattern is exposed to air from a surface of the resin.

10. (Withdrawn) The method of producing a semiconductor device according to claim 9, wherein the patterning of the metal plate is performed by stamping or etching.

11 and 12. (Cancelled)

13. (Withdrawn) The method of producing a semiconductor device according to claim 9, wherein the step of bonding and fixing a part of one side of the coil pattern using sheets of tape is carried out after the connecting terminal pattern and the IC chip are electrically connected.

14. (Currently Amended, Withdrawn) A method of producing a semiconductor device that transmits information by using as a transmission medium an induction field generated from a coil electrically connected to an IC chip for storing and processing information to be transmitted, comprising the steps of:

preparing one sheet of a metal plate;

forming a metal frame having at least a coil pattern, an IC chip supporting section, a connecting terminal pattern formed at an end of the coil pattern, and a tying section tying respective portions of the coil pattern, by patterning the metal plate;

mounting the IC chip on the IC chip supporting section;

electrically connecting the connecting terminal pattern to the IC chip using wires;

bonding and fixing a part of one side of the coil pattern using sheets of tape after the connecting terminal pattern and the IC chip are electrically connected;

cutting the tying section; and

integrating the IC chip, the IC chip supporting section, the coil pattern, the wires, the sheets of tape and the metal frame with a resin such that at least one side of the coil pattern is exposed to air from a surface of the resin.

15. (Currently Amended, Withdrawn) A method of producing a semiconductor device that transmits information by using as a transmission medium an induction field generated from a coil electrically connected to an IC chip for storing and processing information to be transmitted, comprising the steps of:

preparing one sheet of a metal plate;

forming a metal frame having at least a coil pattern, an IC chip supporting section, a connecting terminal pattern formed at an end of the coil pattern, an outer frame section, and tying sections tying respective portions of the coil pattern and tying the coil pattern and the outer frame section, by patterning the metal plate;

mounting the IC chip on the IC chip supporting section;

electrically connecting the connecting terminal pattern to the IC chip using wires;

bonding and fixing a part of one side of the coil pattern using sheets of tape after the connecting terminal pattern and the IC chip are electrically connected;

cutting the tying section tying respective portions of the coil pattern;

integrating the IC chip, the IC chip supporting section, the coil pattern, the wires, the sheets of tape and the metal frame with a resin such that at least one side of the coil pattern is exposed to air from a surface of the resin; and

cutting the tying section tying the coil pattern and the outer frame section.

16. (Withdrawn) The method of producing a semiconductor device according to claim 15, wherein a plurality of semiconductor devices is produced from the one sheet of the metal plate.

17. (Cancelled)

18. (Currently Amended) An electrophotographic apparatus on which a detachable process cartridge is mounted, comprising:

(i) a semiconductor device including an IC chip for storing and processing information to be transmitted, the semiconductor device comprising:

(a) an IC chip supporting section for mounting the IC chip thereon;

(b) a coil for generating an induction field;

(c) connecting terminals provided at an end of the coil;

(d) wires connecting the IC chip and the connecting terminals;

(e) sheets of tape bonding and fixing a part of one side of the coil; and

(f) a resin integrating the IC chip, the IC chip supporting section, the coil, the wires, the connecting terminals, and the sheets of tape with one another,

wherein the IC chip supporting section, the coil, and the connecting terminals are formed of the same metal plate that is patterned, and

wherein at least one side of the coil is exposed to air from a surface of the resin;

(ii) the process cartridge on which the semiconductor device is stuck; and

(iii) a transmission-reception unit for receiving information from and transmitting information to the semiconductor device.